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Application No.: 10/755,042

Docket No.: JCLA8533-D2

JUL 20 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:)
Mou-Shiung Lin et al.)
Serial No. : 10/755,042)
Filed : January 9, 2004)
For : INTEGRATED CHIP PACKAGE)
STRUCTURE USING SILICON)
SUBSTRATE AND METHOD OF)
MANUFACTURING THE SAME)

Examiner : FENTY, JESSE A.

Art Unit : 2815

Docket No. : JCLA8533-D2

*See Request
entry 7/20/05*

AMENDMENT AFTER FINAL

MAIL STOP AF
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The Office Action mailed April 20, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

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